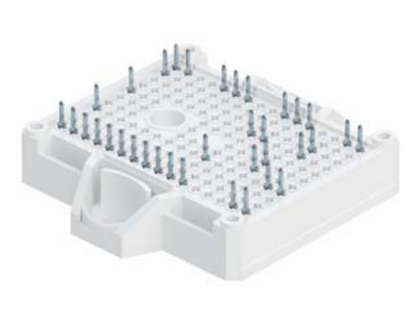
SK50DGDL12T7ETE2s



SEMITOP®E2 Solder

3-phase Converter-Inverter-Brake (CIB)

SK50DGDL12T7ETE2s

Features*

- Optimized design for superior thermal performance
- Low inductive design
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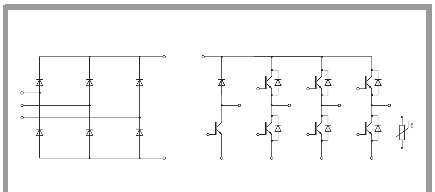
- 1200V Generation 7 IGBT (T7)
- Robust and soft switching CAL4F diode technology
- PEP rectifier diode technology for enhanced power and environmental robustness
- Integrated NTC temperature sensor
- UL recognized file no. E 63 532

Typical Applications

- Motor drives
- Air conditioning
- Auxiliary Inverters

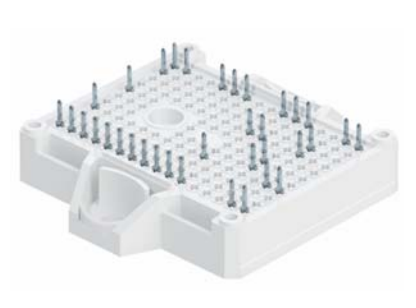
Remarks

- Recommended $T_{j,op}$ = -40 ...+150 °C
- $T_{j,op}$ > 150 °C during overload (details on AN19-002)



DGDL-ET

Absolute Maximum Ratings				
Symbol	**Conditions**		**Values**	**Unit**
Inverter - IGBT				
V_{CES}	T_j = 25 °C		1200	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 70 °C	55	A
		T_s = 100 °C	45	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 70 °C	69	A
		T_s = 100 °C	56	A
I_{Cnom}			50	A
I_{CRM}			100	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V V_{GE} ≤ 15 V V_{CES} ≤ 1200 V	T_j = 175 °C	7	µs
T_j			-40 ... 175	°C
Chopper - IGBT				
V_{CES}	T_j = 25 °C		1200	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 70 °C	55	A
		T_s = 100 °C	45	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 70 °C	69	A
		T_s = 100 °C	56	A
I_{Cnom}			50	A
I_{CRM}			100	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V V_{GE} ≤ 15 V V_{CES} ≤ 1200 V	T_j = 175 °C	7	µs
T_j			-40 ... 175	°C
Inverse - Diode				
V_{RRM}	T_j = 25 °C		1200	V
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 70 °C	33	A
		T_s = 100 °C	27	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 70 °C	39	A
		T_s = 100 °C	32	A
I_{FRM}			100	A
I_{FSM}	t_p = 10 ms, sin 180°, T_j = 150 °C		170	A
T_j			-40 ... 175	°C
Freewheeling - Diode				
V_{RRM}	T_j = 25 °C		1200	V
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 70 °C	17	A
		T_s = 100 °C	14	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 70 °C	20	A
		T_s = 100 °C	16	A
I_{FRM}			45	A
I_{FSM}	t_p = 10 ms, sin 180°, T_j = 150 °C		65	A
T_j			-40 ... 175	°C



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SK50DGDL12T7ETE2s

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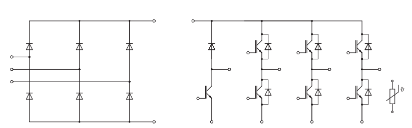


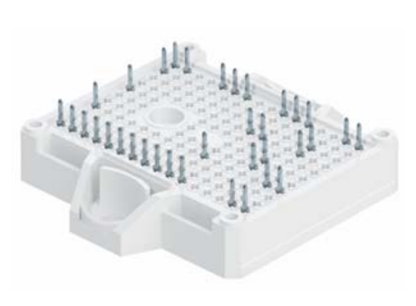
DGDL-ET

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Rectifier - Diode				
V_{RRM}	T_j = 25 °C		1600	V
I_F	λ_{paste}=0.8 W/(mK)	T_s = 70 °C	59	A
	T_j = 175 °C	T_s = 100 °C	46	A
I_F	λ_{paste}=2.5 W/(mK)	T_s = 70 °C	73	A
	T_j = 175 °C	T_s = 100 °C	57	A
I_{FSM}	t_p = 10 ms	T_j = 25 °C	520	A
	sin 180°	T_j = 150 °C	350	A
i^2t	t_p = 10 ms	T_j = 25 °C	1350	A^2s
	sin 180°	T_j = 150 °C	613	A^2s
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$	, $\Delta T_{terminal}$ at PCB joint = 30 K, per pin		30	A
T_{stg}	module without TIM		-40 ... 125	°C
V_{isol}	AC, sinusoidal, 1 min		2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	I_C = 50 A	T_j = 25 °C		1.55	1.70	V
	V_{GE} = 15 V	T_j = 150 °C		1.73	1.88	V
	chiplevel	T_j = 175 °C		1.77	1.92	V
V_{CE0}		T_j = 25 °C		1.00	1.05	V
	chiplevel	T_j = 150 °C		0.80	0.85	V
		T_j = 175 °C		0.75	0.80	V
r_{CE}	V_{GE} = 15 V	T_j = 25 °C		11	13	mΩ
	chiplevel	T_j = 150 °C		19	21	mΩ
		T_j = 175 °C		20	22	mΩ
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 1.27 mA		5.15	5.8	6.45	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C				1	mA
C_{ies}	V_{CE} = 25 V	f = 1 MHz		10.00		nF
C_{oes}	V_{GE} = 0 V	f = 1 MHz		0.13		nF
C_{res}		f = 1 MHz		0.04		nF
Q_G	V_{GE} = -15 V ... +15 V			798		nC
R_{Gint}	T_j = 25 °C			0		Ω
$t_{d(on)}$	V_{CC} = 600 V	T_j = 25 °C		39		ns
	I_C = 50 A	T_j = 150 °C		40		ns
	$R_{G\,on}$ = 5.1 Ω	T_j = 175 °C		41		ns
t_r	$R_{G\,off}$ = 5.1 Ω	T_j = 25 °C		37		ns
	V_{GE} = +15/-15 V	T_j = 150 °C		41		ns
	(T_j = 150 °C)	T_j = 175 °C		42		ns
E_{on}	di/dt_{on} = 990 A/µs	T_j = 25 °C		3.04		mJ
	di/dt_{off} = 440 A/µs	T_j = 150 °C		4.59		mJ
	dv/dt = 4500 V/µs	T_j = 175 °C		5.16		mJ



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Typical Applications

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- Auxiliary Inverters

Remarks

- Recommended $T_{j,op}$ = -40 ...+150 °C
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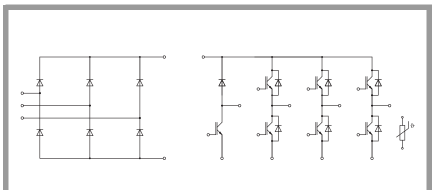
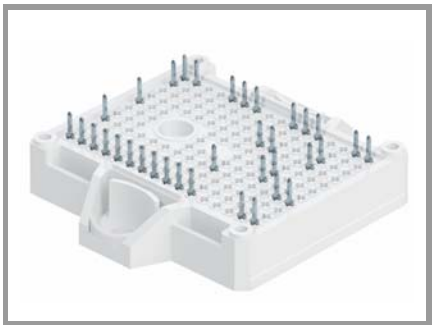


DGDL-ET

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Inverter - IGBT						
$t_{d(off)}$	V_{CC} = 600 V I_C = 50 A $R_{G\,on}$ = 5.1 Ω $R_{G\,off}$ = 5.1 Ω V_{GE} = +15/-15 V (T_j = 150 °C) di/dt$_{on}$ = 990 A/µs di/dt$_{off}$ = 440 A/µs dv/dt = 4500 V/µs	T_j = 25 °C		204		ns
		T_j = 150 °C		271		ns
		T_j = 175 °C		281		ns
t_f		T_j = 25 °C		41		ns
		T_j = 150 °C		65		ns
		T_j = 175 °C		89		ns
E_{off}		T_j = 25 °C		3.21		mJ
		T_j = 150 °C		5.28		mJ
		T_j = 175 °C		5.59		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.94		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.66		K/W
Chopper - IGBT						
$V_{CE(sat)}$	I_C = 50 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.55	1.70	V
		T_j = 150 °C		1.73	1.88	V
		T_j = 175 °C		1.77	1.92	V
V_{CE0}	chiplevel	T_j = 25 °C		1.00	1.05	V
		T_j = 150 °C		0.80	0.85	V
		T_j = 175 °C		0.75	0.80	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		11	13	mΩ
		T_j = 150 °C		19	21	mΩ
		T_j = 175 °C		20	22	mΩ
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 1.27 mA		5.15	5.8	6.45	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C				1	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		10.00		nF
C_{oes}		f = 1 MHz		0.13		nF
C_{res}		f = 1 MHz		0.04		nF
Q_G	V_{GE} = -15 V ... +15 V			798		nC
R_{Gint}	T_j = 25 °C			0		Ω
$t_{d(on)}$	V_{CC} = 600 V I_C = 50 A $R_{G\,on}$ = 5.1 Ω $R_{G\,off}$ = 5.1 Ω V_{GE} = +15/-15 V (T_j = 150 °C) di/dt$_{on}$ = 990 A/µs di/dt$_{off}$ = 440 A/µs dv/dt = 4500 V/µs	T_j = 25 °C		39		ns
		T_j = 150 °C		40		ns
		T_j = 175 °C		41		ns
t_r		T_j = 25 °C		37		ns
		T_j = 150 °C		41		ns
		T_j = 175 °C		42		ns
E_{on}		T_j = 25 °C		3.04		mJ
		T_j = 150 °C		4.59		mJ
		T_j = 175 °C		5.16		mJ
$t_{d(off)}$		T_j = 25 °C		204		ns
		T_j = 150 °C		271		ns
		T_j = 175 °C		281		ns
t_f		T_j = 25 °C		41		ns
		T_j = 150 °C		65		ns
		T_j = 175 °C		89		ns
E_{off}		T_j = 25 °C		3.21		mJ
		T_j = 150 °C		5.28		mJ
		T_j = 175 °C		5.59		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.94		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.66		K/W



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Remarks

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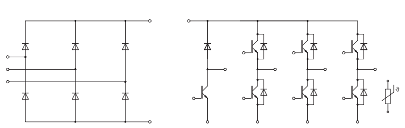
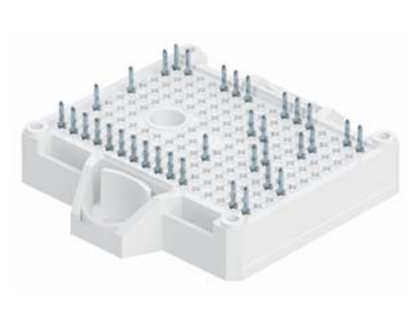
- $T_{j,op}$ > 150 °C during overload (details on AN19-002)



DGDL-ET

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
$V_F = V_{EC}$	I_F = 50 A	T_j = 25 °C		2.73	3.10	V
		T_j = 150 °C		2.89	3.27	V
	chiplevel	T_j = 175 °C		2.71	3.09	V
V_{F0}		T_j = 25 °C		1.30	1.50	V
	chiplevel	T_j = 150 °C		0.90	1.10	V
		T_j = 175 °C		0.82	0.98	V
r_F		T_j = 25 °C		29	32	mΩ
	chiplevel	T_j = 150 °C		40	43	mΩ
		T_j = 175 °C		38	42	mΩ
I_{RRM}	V_{CC} = 600 V I_F = 50 A V_{GE} = -15 V (T_j = 150 °C) di/dt$_{off}$ = 1010 A/µs	T_j = 25 °C		23		A
		T_j = 150 °C		31		A
		T_j = 175 °C		32		A
Q_{rr}		T_j = 25 °C		1.84		µC
		T_j = 150 °C		5.43		µC
		T_j = 175 °C		6.13		µC
E_{rr}		T_j = 25 °C		0.67		mJ
		T_j = 150 °C		2.41		mJ
		T_j = 175 °C		2.53		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			1.34		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			1.01		K/W
Freewheeling - Diode						
$V_F = V_{EC}$	I_F = 15 A	T_j = 25 °C		2.38	2.71	V
		T_j = 150 °C		2.44	2.77	V
	chiplevel	T_j = 175 °C		2.26	2.58	V
V_{F0}		T_j = 25 °C		1.30	1.50	V
	chiplevel	T_j = 150 °C		0.90	1.10	V
		T_j = 175 °C		0.82	0.98	V
r_F		T_j = 25 °C		72	81	mΩ
	chiplevel	T_j = 150 °C		103	111	mΩ
		T_j = 175 °C		96	107	mΩ
I_{RRM}	V_{CC} = 600 V I_F = 15 A V_{GE} = -15 V (T_j = 150 °C) di/dt$_{off}$ = 880 A/µs	T_j = 25 °C		11		A
		T_j = 150 °C		15		A
		T_j = 175 °C		18		A
Q_{rr}		T_j = 25 °C		1.03		µC
		T_j = 150 °C		2.29		µC
		T_j = 175 °C		2.58		µC
E_{rr}		T_j = 25 °C		0.31		mJ
		T_j = 150 °C		0.97		mJ
		T_j = 175 °C		1.49		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			2.13		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			1.74		K/W



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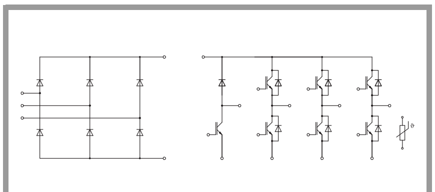


DGDL-ET

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Rectifier - Diode						
V_F	I_F = 50 A chiplevel	T_j = 25 °C		1.11	1.40	V
		T_j = 150 °C		1.05	1.34	V
		T_j = 175 °C		1.05	1.35	V
V_{F0}	chiplevel	T_j = 25 °C		0.89	1.09	V
		T_j = 150 °C		0.73	0.92	V
		T_j = 175 °C		0.69	0.88	V
r_F	chiplevel	T_j = 25 °C		4.5	6.1	mΩ
		T_j = 150 °C		6.3	8.6	mΩ
		T_j = 175 °C		7.2	9.4	mΩ
I_R	T_j = 150 °C, V_{RRM}				2	mA
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			1.24		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			0.92		K/W
Module						
M_s	to heatsink		1.6		2.3	Nm
w				35		g
L_{CE}				30		nH
Temperature Sensor						
R_{100}	T_c=100°C (R_{25}=5 kΩ)			493 ± 5%		Ω
$B_{25/85}$	$R_{(T)}$=R_{25}*exp[$B_{25/85}$*(1/T-1/298)], T[K]			3420		K

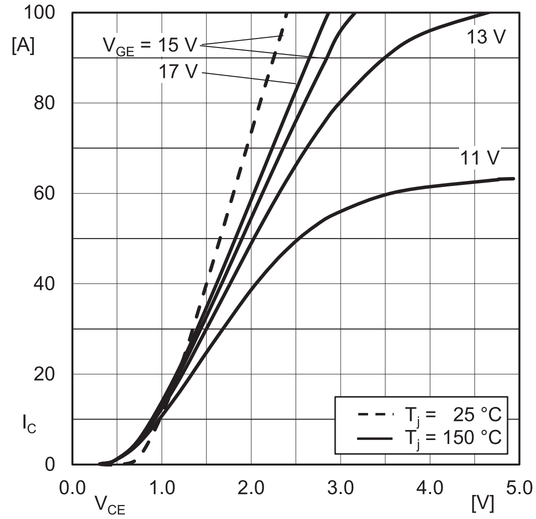


Fig. 1: Typ. IGBT output characteristic, incl. $R_{CC+EE'}$

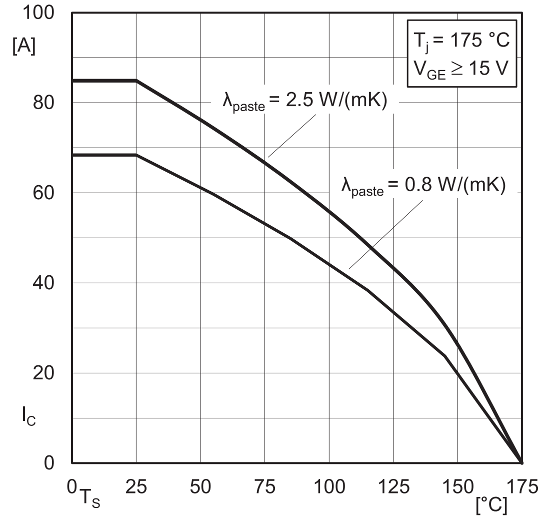


Fig. 2: IGBT rated current vs. temperature I_c=f(T_s)

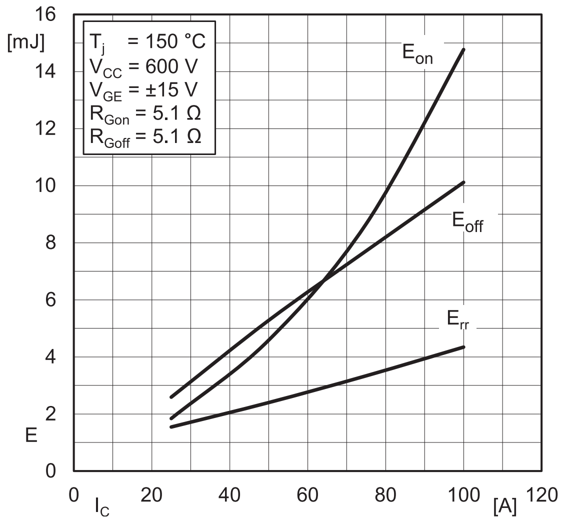


Fig. 3: Typ. turn-on /-off energy = f (I_C)

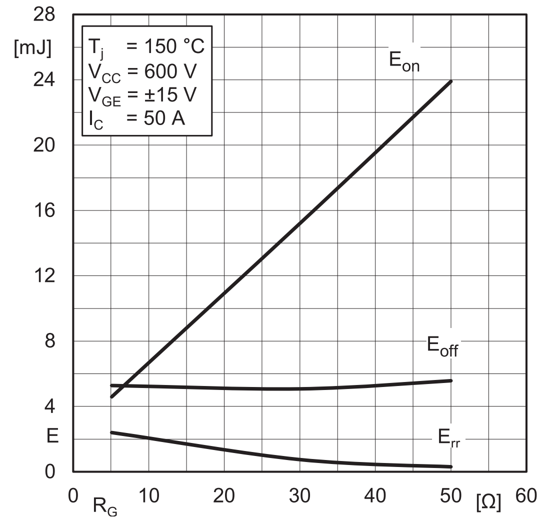


Fig. 4: Typ. turn-on /-off energy = f (R_G)

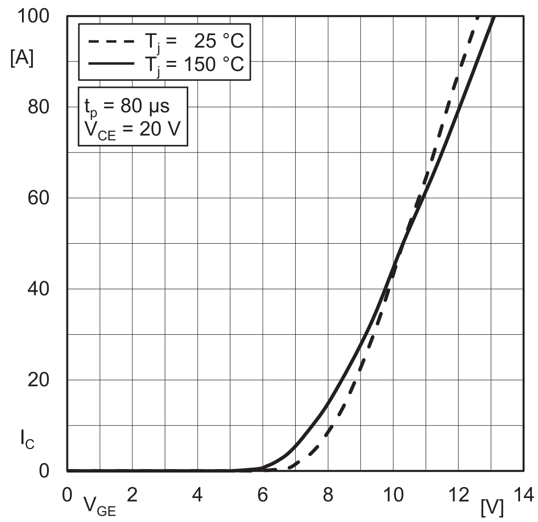


Fig. 5: Typ. IGBT transfer characteristic

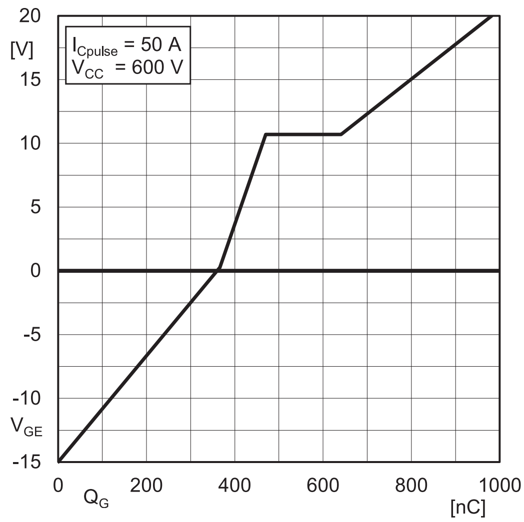


Fig. 6: Typ. IGBT gate charge characteristic

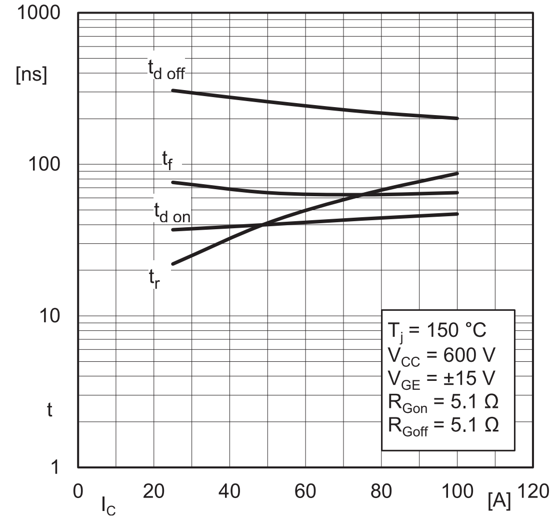


Fig. 7: Typ. switching times = f (I_C)

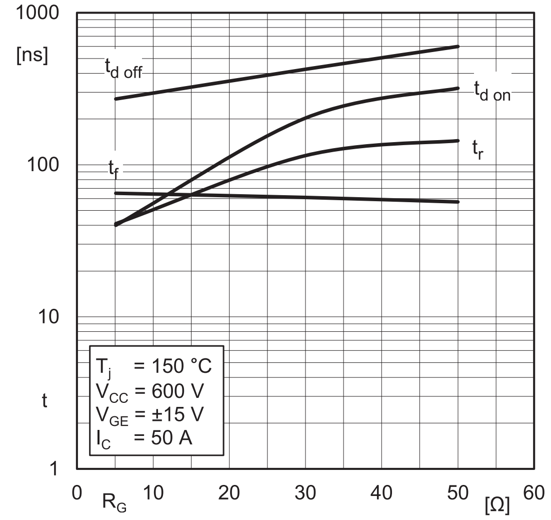


Fig. 8: Typ. switching times = f (R_G)

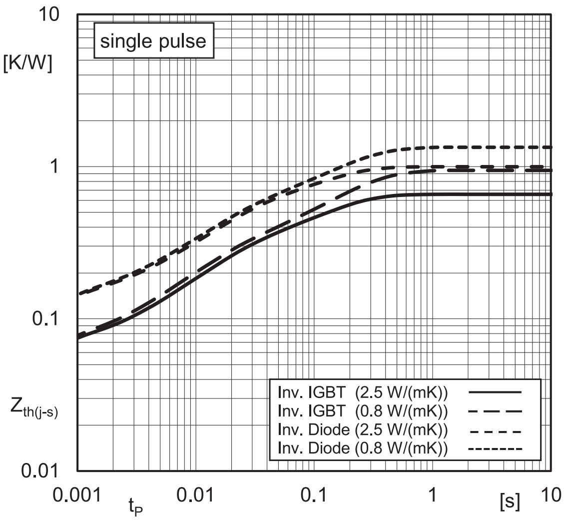


Fig. 9: Typ. transient thermal impedance

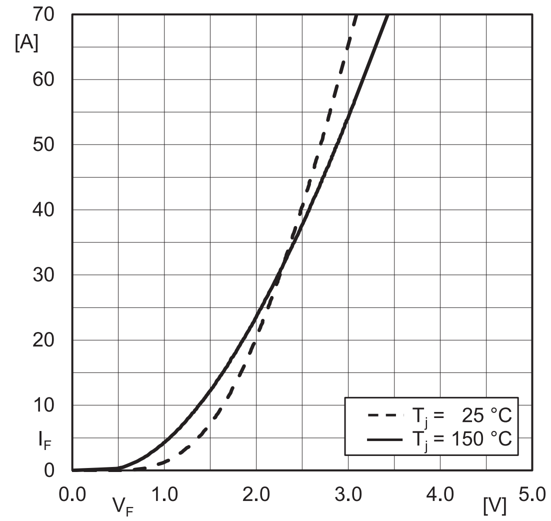


Fig. 10: Typ. Inv. diode forward charact., incl. $R_{CC'+EE'}$

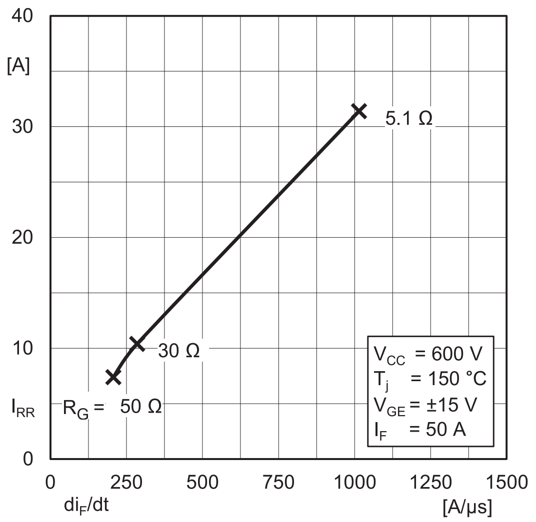


Fig. 11: Typ. Inv. diode peak reverse recovery current

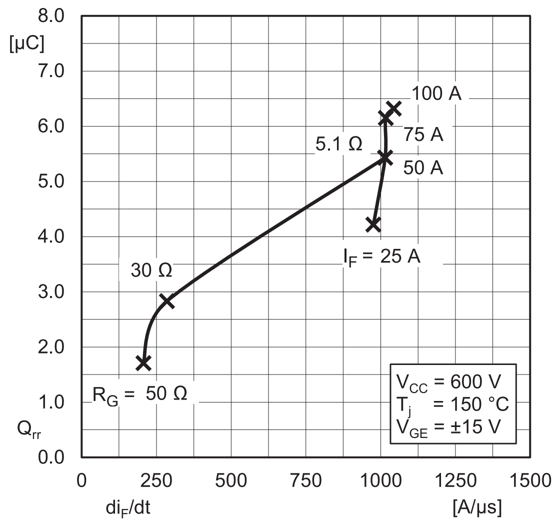


Fig. 12: Typ. Inv. diode reverse recovery charge

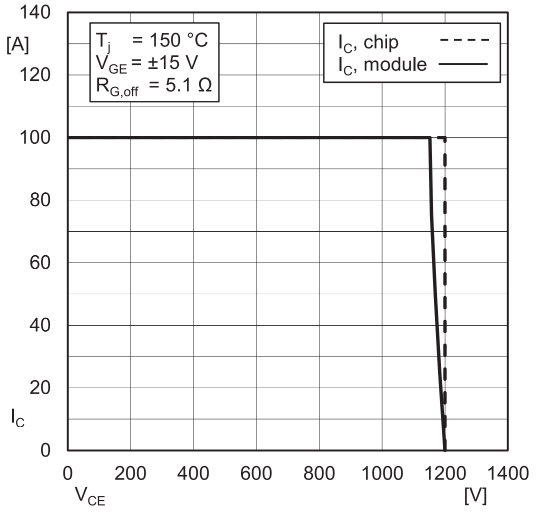


Fig. 13: IGBT Reverse Bias Safe Operating Area (RBSOA)

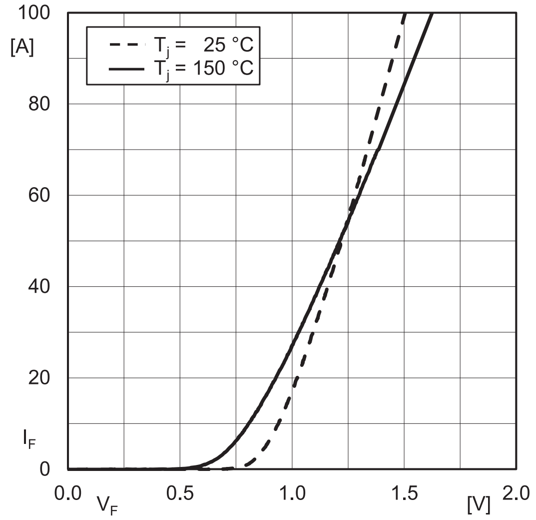
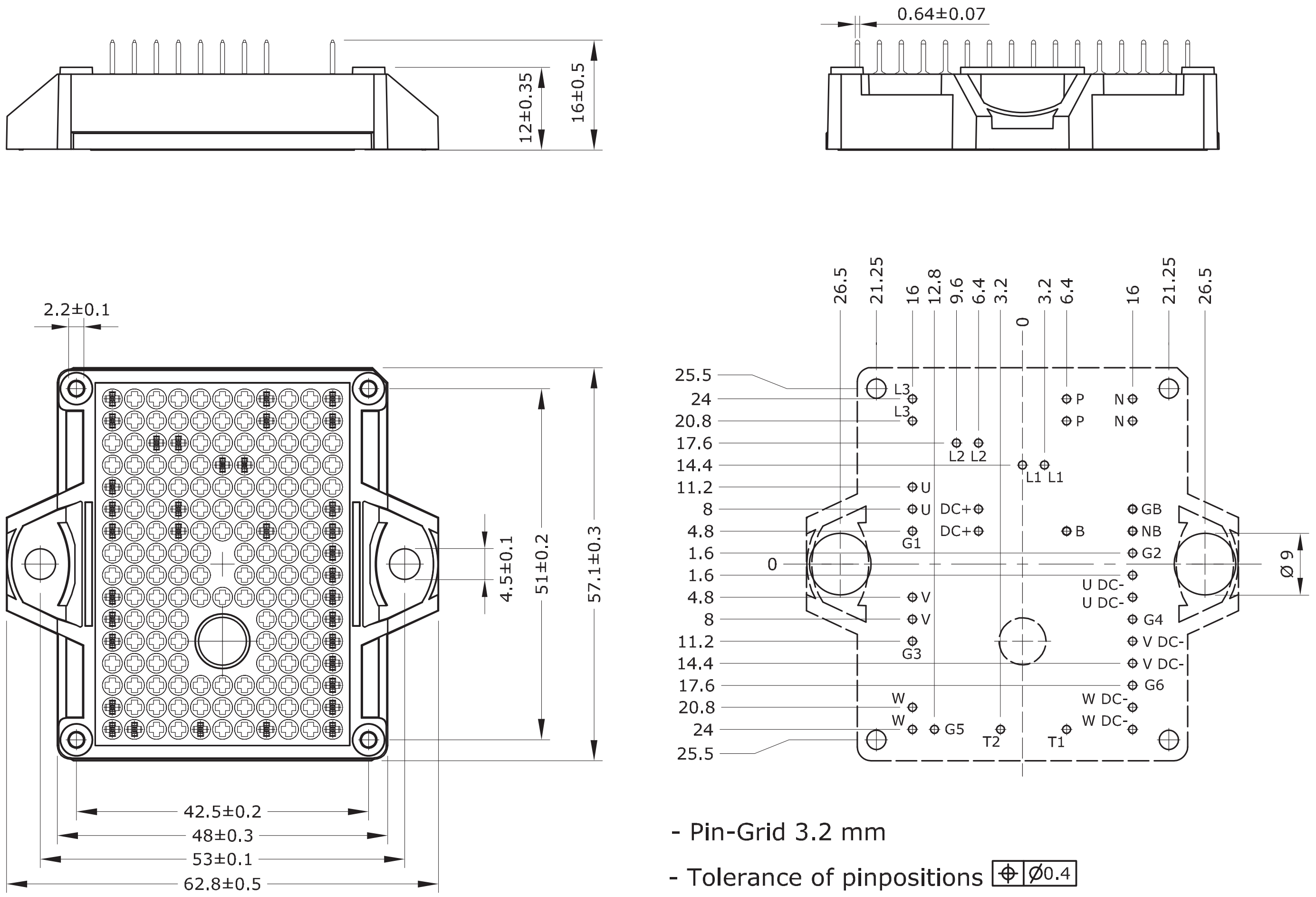
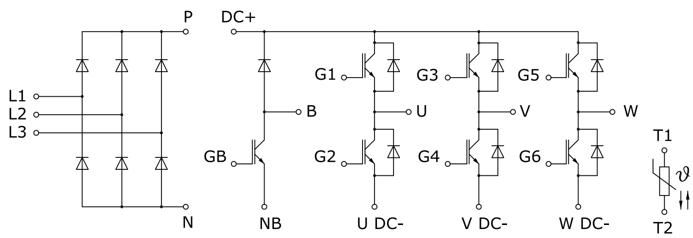


Fig. 14: Typ. Rect. diode forward charact., incl. $R_{CC'+ EE'}$



- Pin-Grid 3.2 mm
- Tolerance of pinpositions ⌖ Ø0.4

SEMITOP®E2 Solder



DGDL-ET

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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